

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6523823

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEXANDER GOVYADINOV	05/21/2010
ERIK TORNIAINEN	05/24/2010
DAVID P MARKEL	05/24/2010
RECEIVING PARTY DATA	
Name:	Hewlett-Packard Development Company, L.P.
Street Address:	10300 Energy Drive
City:	Spring
State/Country:	TEXAS
Postal Code:	77389
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17065831
CORRESPONDENCE DATA	
Fax Number:	(970)778-4063
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(541)360-4450
Email:	ipa.mail@hp.com
Correspondent Name:	HP INC.
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Address Line 4:	FORT COLLINS, COLORADO 80528
ATTORNEY DOCKET NUMBER:	85947693
NAME OF SUBMITTER:	JESSICA PAZDAN
SIGNATURE:	/JESSICA PAZDAN/
DATE SIGNED:	01/29/2021
Total Attachments: 3	
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source=85947693#page3.tif	

HEWLETT-PACKARD COMPANY
Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

ATTORNEY DOCKET NO. 85947693

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each) have agreed and hereby agree to assign to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPDC), in furtherance of my/our obligations to the Hewlett-Packard Company and its subsidiaries and affiliates, and do hereby assign and transfer to HPDC, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

FLUID EJECTION DEVICE INCLUDING RECIRCULATION SYSTEM

Filing Date: May 21, 2010 Application No.: PCT/US2010/035697

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

I/we additionally authorize HPDC to file applications in my/our name for Letters Patent in any country, to be held and enjoyed by HPDC, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to HPDC, its successors, assigns, nominees or legal representatives; and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC;

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.


Inventor's Signature 05/21/2010
Date Assignment Signed

Alexander GOVYADINOV
Inventor's Typed Name 05/21/2010
Date Application Signed

Inventor's Signature _____
Date Assignment Signed

Erk D. TORNIAINEN
Inventor's Typed Name _____
Date Application Signed

HEWLETT-PACKARD COMPANY
 Intellectual Property Administrator
 3404 E. Harmony Road
 Mail Stop 35
 Fort Collins, Colorado 80528

PATENT APPLICATION

ATTORNEY DOCKET NO. _____

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FLUID EJECTION DEVICE INCLUDING RECIRCULATION SYSTEM

Filing Date: _____ Application No.: _____

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

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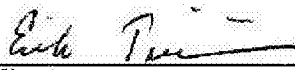
AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent; to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC;

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.

Inventor's Signature _____ Date Assignment Signed _____

Alexander GOVYADINOV
Inventor's Typed Name _____ Date Application Signed _____


 Inventor's Signature _____ Date Assignment Signed 5/24/10

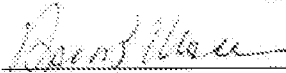
Erik D. TORNIAINEN
Inventor's Typed Name _____ Date Application Signed 5/24/10

HEWLETT-PACKARD COMPANY
Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

ATTORNEY DOCKET NO. _____

ASSIGNMENT OF PATENT APPLICATION (cont.)


Inventor's Signature _____ 5/24/2010
Date Assignment Signed _____

David P. MARKEL
Inventor's Typed Name _____ 5/24/2010
Date Application Signed _____

Inventor's Signature _____ Date Assignment Signed _____

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